RUMP SESSIONS

Technology and Circuits Joint Rump Session

RJ1 SOC (System-On-a-Chip) versus SIP (System-In-a-Package)

Organizers/ Moderators:

Circuits:	**Technology:**
J. Goodman, Lumic Electronics	D. Buss, Texas Instruments
T. Sakurai, University of Tokyo	T. Suga, University of Tokyo

In the Internet Age, growth areas for solid-state circuits are in personal internet products (e.g., cell phones, PDAs, Internet audio players, and portable video players/recorders) and the networks used to connect these products (e.g., short distance wireless, DSL modems, cable modems, and eventually fiber to the home and office). These applications all require integration to achieve cost reduction. The panel will explore the question of whether cost reduction will result from SoC integration or SiP integration, or through a new kind of integration called heterogeneous integration.

Panelists:

T. Furuyama, Toshiba
H. Kawamoto, FAIS
W. Kurjanowicz, ATMOS Corp.

R. Markunas, Ziptronix
A. Matsuzawa, Panasonic
R. Pitts, Texas Instruments

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